



N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)	Q _g (Typ)		
30	$0.0040 \text{ at V}_{GS} = 10 \text{ V}$	25	47		
	0.0048 at V _{GS} = 4.5 V	23	47		

FEATURES

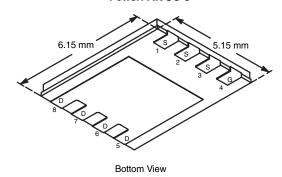
- TrenchFET[®] Power MOSFET
- Optimized for "Low Side" Synchronous Rectifier Operation



100 % R_g Tested



PowerPAK SO-8

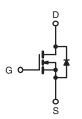


Ordering Information: Si7886ADP-T1

Si7886ADP-T1-E3 (Lead (Pb)-Free)

FEATURES

- DC/DC Converters
- · Synchronous Rectifiers



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ess otherwise	noted		
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage		V_{DS}	30		V
Gate-Source Voltage		V_{GS}	± 12		V
Continuous Drain Current (T, = 150 °C) ^a	T _A = 25 °C	I _D	25	15	
Continuous Drain Current (1) = 150 °C)	T _A = 70 °C		20	12	
Pulsed Drain Current (10 μs Pulse Width)		I _{DM}	60		Α
Continuous Source Current (Diode Conduction) ^a		I _S	4.5	1.6	
Avalanche Current	L = 0.1 mH	I _{AS}	I _{AS} 50		
Single Pulse Avalanche Energy	L = 0.111111	E _{AS}	125		mJ
Marrian Danier Discipation 8	T _A = 25 °C	P _D	5.4	1.9	W
Maximum Power Dissipation ^a	T _A = 70 °C	ם י ט	3.4	1.2	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b,c}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Manianum lumation to Austrianti	t ≤ 10 sec	R _{thJA}	18	23	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		50	65		
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.0	1.5		

Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

Vishay Siliconix

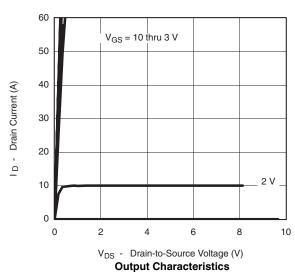


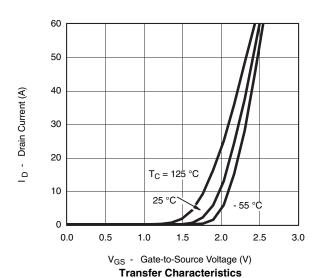
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static					l		
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6	1	1.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zara Cata Valtana Busin Our	l	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
Drain-Source On-State Resistance ^a	_	V _{GS} = 10 V, I _D = 25 A		0.0032	0.0040	-	
	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 23 \text{ A}$		0.0037	0.0048	Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 25 \text{ A}$		90		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 2.9 A, V _{GS} = 0 V		0.7	1.1	V	
Dynamic ^b			•				
Input Capacitance	C _{iss}			6450			
Output Capacitance	$V_{DS} = 15 \text{ V}, V_{SS} = 0 \text{ V}, f = 1 \text{ kHz}$		873		pF		
Reverse Transfer Capacitance	C _{rss}	C _{rss}		402			
Total Gate Charge	Qg			47	60	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 25 \text{ A}$		12.5			
Gate-Drain Charge	Q_{gd}			9.0			
Gate Resistance	R_{g}		0.5	1.0	1.5	Ω	
Turn-On Delay Time	t _{d(on)}			17	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		14	25		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1.0 A, V_{GEN} = 10 V, R_G = 6 Ω		158	230	ns	
Fall Time	t _f			43	65	110	
Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 2.9 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		50	80		

- Notes: a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless noted



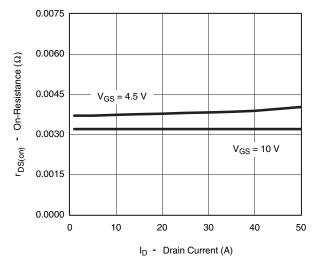




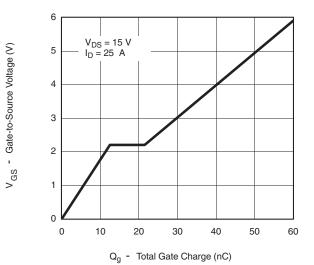




TYPICAL CHARACTERISTICS 25 °C, unless noted



On-Resistance vs. Drain Current



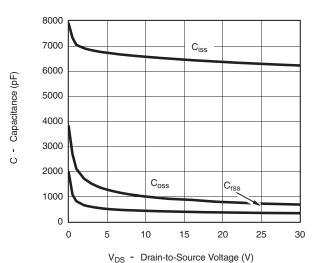
T_J = 150 °C

T_J = 25 °C —

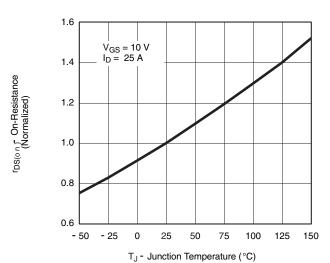
T_J = 25 °C —

Gate Charge

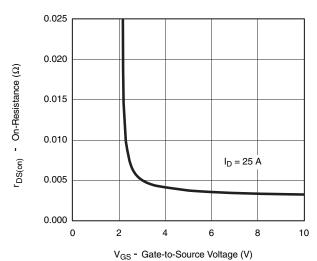
 V_{SD} - Source-to-Drain Voltage (V) Source-Drain Diode Forward Voltage



Capacitance



On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

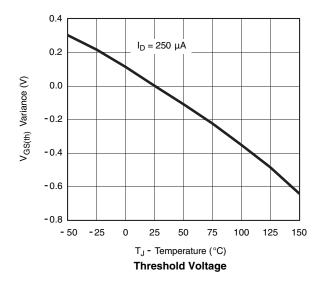
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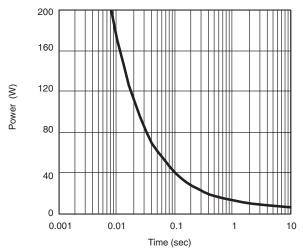
Is - Source Current (A)

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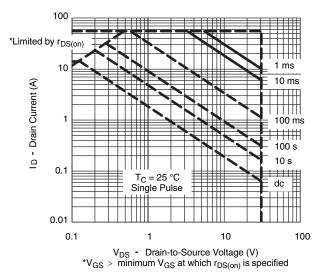
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TYPICAL CHARACTERISTICS 25 °C, unless noted

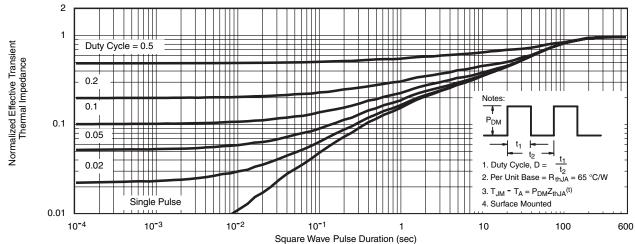




Single Pulse Power, Junction-to-Ambient



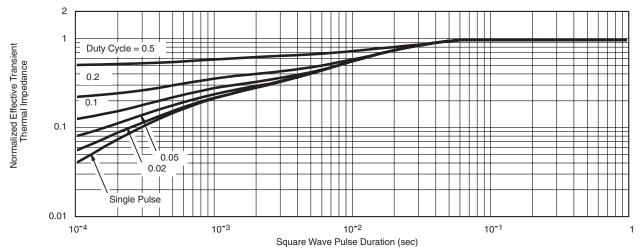
Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless noted



Normalized Thermal Transient Impedance, Junction-to-Case

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